

Hiner-pack® FVWS Canister 300 mm

Reliable wafer shipping solution ensuring protection from contamination and mechanical damage

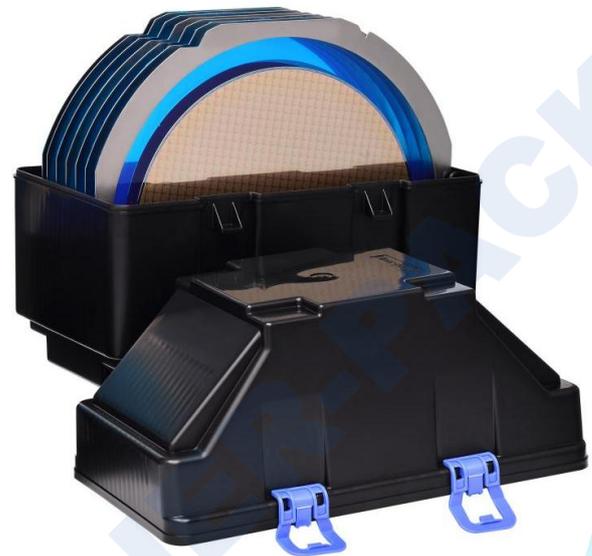
Engineered for wafers mounted on flex, dicing, or film frame, this vertical shipper secures frame-supported wafers in a standing orientation. Its precision-molded slots immobilize frames, its inner contours cradle the metal or plastic frame rather than the wafer surface, preventing wafer slippage and micro-crack damage during handling. Spring design in the upper cover can effectively avoid the frames movement, prevent wafer breakage. Made from ESD-protective polymer materials, which can resist ionic contamination, outgassing, and static discharge. Dust-free cleaning and packaging after completion of production, suitable for 100-class purification workshop, ensures particle-free storage, which is critical in maintaining the integrity of sensitive wafers throughout the shipping process. Flex Frame Wafer Shippers are the ideal solution for semiconductor manufacturers seeking reliable and efficient transportation of multiple wafers mounted on dicing, flex, or film frames.

SPECIFICATIONS

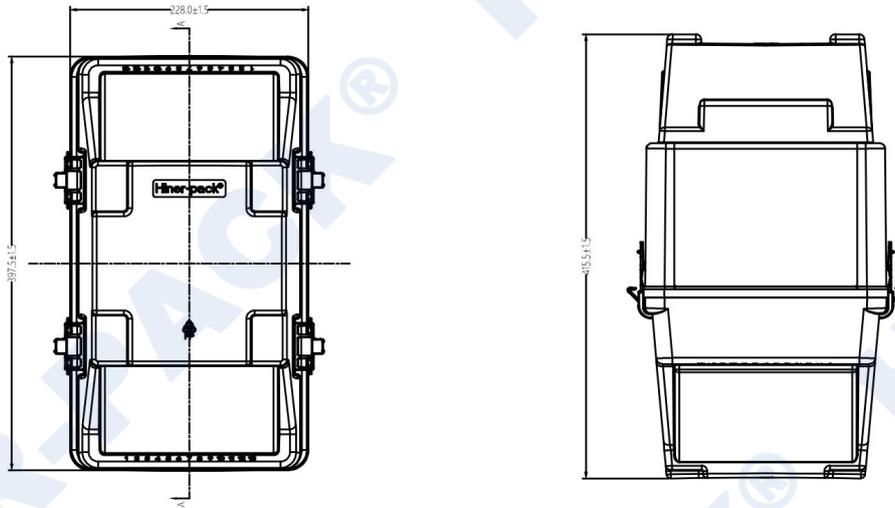
- 397.5 mm L × 228 mm W × 415.5 mm H (15.65" × 8.98" × 16.36")
- Maximum load capacity is 13 pieces
- Sold in full case quantity (2)

FEATURES & BENEFITS

- Made from low particles/ionic/outgassing material
- Vertical secures wafers already mounted on flex, dicing, or film frame
- Spring design in the upper cover can effectively avoid the frames movement, prevent wafer breakage
- Reusable for cost-efficient shipping



DIMENSION



BASIC INFORMATION

Part Number	Collocation Reference	Wafer Size
FVWS-12/13-BL	Bottom+Frame+Top	300 mm

REFERENCE ILLUSTRATION

300mm Wafer (With Flex Frame Ring and Blue Tape/ UV Curing)



The above illustration is for reference only. Please refer to the actual product for accuracy.

TECHNICAL DATA

PROPERTY	TEST METHOD	RATED VALUES
Density	ISO 1183-1 (23°C)	1.0 g/cm ³
Melt Index (350°C/5kg)	ASTM D-1238	15.0 g/10min
Shrinkage Percentage	ISO 2577	1.2~1.6 %
Tensile Strength	ISO 527-2 (50mm/min)	25 MPa
Tensile Strain at Break	ISO 527-2 (50mm/min)	10 %
Flexural Strength (Fracture)	ISO 178 (2mm/min)	27 MPa
Flexural Modulus	ISO 178 (2mm/min)	1150 MPa
LZOD Notch Impact Strength (3.2mm)	ISO 180 (23°C)	30 kJ/m ²
Surface Resistivity	ASTM D-257	1.0×10 ⁴ ~1.0×10 ⁹ Ω/sq
Flame Retardant Rating	UL 94	HB Class

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.



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